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FORM PTO-1596  
1-31-92

RF

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

Docket No.: 50395-059

101478884

To the Honorable Commissioner of Patents and Trademarks: Please receive \_\_\_\_\_ and original documents or copy thereto:

## 1. Name of Conveying Party:

Hideo HARUTA

Additional name(s) of conveying party(ies) attached? ☐ Yes

## 3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: July 6, 2000

## 2. Name and address of receiving party:

Name: SUMITOMO ELECTRIC FINE POLYMER, INC.

Address: 950, Oaza Noda, Kumatori-cho

Sennan-gun

Osaka, Japan

Additional name(s) & address(es) attached? ☐ Yes

## 4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is:

## A. Patent Application No(s).

09/570,542, filed May 12, 2000

## B. Patent No(s).

Additional numbers attached? ☐ Yes

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL &amp; EMERY

Internal Address:

Street Address: 600 13<sup>th</sup> Street, N.W.

City: Washington State: DC Zip: 20005

## 6. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

## 8. Deposit account number:

500417

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## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Arthur J. Steiner, 26,106

Name and Registration No. of Person Signing



Signature

August 11, 2000

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

10/03/2000 GTOW11 00000050 500417 09570542  
01 FC:581 40.00 CHPATENT  
REEL: 011120 FRAME: 0591

10003691.00  
Docket No.: 50395-059

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Hideo HARUTA

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who has made a certain new and useful invention, hereby sells, assigns and transfers unto

Sumitomo Electric Fine Polymer, Inc.

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950, Oaza Noda, Kumatori-cho

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Sennan-gun, Osaka,

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Japan

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its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

BINDING METAL FOR COVERING WITH HEAT-SHRINKABLE SHEET, PRODUCTION METHOD THEREOF AND COVERING METHOD

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(a) for which an application for United States Letters Patent was filed on May 12, 2000, and identified by United States Serial No. 09/570,542; or

(b) for which an application for United States Letters Patent was executed on ,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR H. Haruta

Hideo HARUTA

DATE SIGNED 6th / July / 2000